

REVISIONS				
REV.	ECN/E-R	DESCRIPTION	DATE	APPROVED
B		CUSTOMER DRAWING	2006/04/05	J.SI
C		UPDATED	2006/08/09	
D		UPDATED	2007/01/02	



**AMPHENOL PART NUMBER CONFIGURATION:**

**UE78 - A 1 1 1 8 - 0 X X X X**

**OPTIONAL DUST COVER**  
 0 - WITHOUT DUST COVER  
 D - WITH DUST COVER (SHIP LOOSE)

**PLATING OPTIONS FOR CONNECTOR**  
 2 - 30µ" GOLD PLATING ON MATING AREA  
 GOLD FLASH ON TERMINATION  
 3 - 30µ" GOLD PLATING ON MATING AREA  
 150-300µ" MATTE TIN ON TERMINATION  
 5 - 15µ" GOLD PLATING ON MATING AREA  
 GOLD FLASH ON TERMINATION  
 6 - 15µ" GOLD PLATING ON MATING AREA  
 150-300µ" MATTE TIN ON TERMINATION

**PACKAGING OPTIONS**  
 T - TAPE AND REEL PACKAGING  
 FOR BOTH CONNECTORS AND  
 CAGES  
 H - TAPE AND REEL FOR  
 CONNECTORS TRAY FOR  
 CAGES

**PLATING OPTIONS FOR CAGE**  
 1 - TIN  
 2 - NICKEL

**MATERIAL (RoHS COMPLIANCE):**

**CAGE:**  
 COPPER ALLOY  
 PLATING OPTION 1: 100µ" [2.54 µm] TIN PLATING OVER  
 50 µ" (1.27 µm) NICKEL UNDER PLATING.  
 PLATING OPTION 2: 100µ" [2.54 µm] NICKEL PLATING  
 (NOT FOR SOLDER PINS).  
**DUST COVER**  
 THERMOPLASTIC, COLOR BLACK.  
**PACKAGING:**  
 TAPE AND REEL OR TRAY PACKAGING.  
 TEMPERATURE RANGE: -40 °C TO +85 °C

**CONNECTOR:**

**PLASTIC HOUSING:**  
 HIGH TEMPERATURE RESISTANT NYLON FLAMMABILITY RATING UL94V-0.  
**CONTACTS:**  
 PHOSPHOR BRONZE  
 PLATING OPTION 2: 30µ" [0.76 µm] GOLD ON MATING AREA AND 2 µ"  
 (0.05 µm) GOLD FLASH PLATING ON TERMINATION OVER  
 50µ"[1.27µm) NICKEL UNDER LAYER.  
 PLATING OPTION 3: 30µ" [0.76 µm] GOLD ON MATING AREA AND  
 150-300 µ" (3.81-7.62 µm) LOW WHISKER MATTE TIN PLATING  
 ON TERMINATION OVER 50µ" [1.27 µm] NICKEL UNDER LAYER.  
 PLATING OPTION 5: 15µ" GOLD PLATING ON MATING AREA  
 GOLD FLASH ON TERMINATION  
 PLATING OPTION 6: 15µ" GOLD PLATING ON MATING AREA  
 150-300µ" (3.81-7.62 µm) MATTE TIN ON TERMINATION  
**PACKAGING:**  
 TAPE AND REEL.  
 TEMPERATURE RANGE: -40 °C TO +85 °C

**DO NOT SCALE DRAWING**

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<b>APPROVALS</b>		<b>DATE</b>	<b>Amphenol Canada Corp.</b>		
DRAWN	A.LIU	2006/02/13			
DESIGNED	J.SI	2006/02/13	TITLE SFP CAGE + CONNECTOR 1X1 8 PRESS FIT / 12 EMI PINS		
CHECKED	J.SI	2006/02/13			
QA APPD	X	X			
IE APPD	X	X	SIZE A3	DWG. NO. P-UE78-A1118-0XXXX	REV. D
DWG APPD			SCALE 2:1	PROJECT	SHEET 1 OF 7



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IE APPD	X	X	SCALE 2:1	PROJECT	SHEET 2 OF 7
DWG APPD					

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⊕ 0.002 [0.06] (M) B A (S) C (S)

⊕ 0.004 [0.10] (S) C D  
(TYP. 20 SOLDER TAILS)

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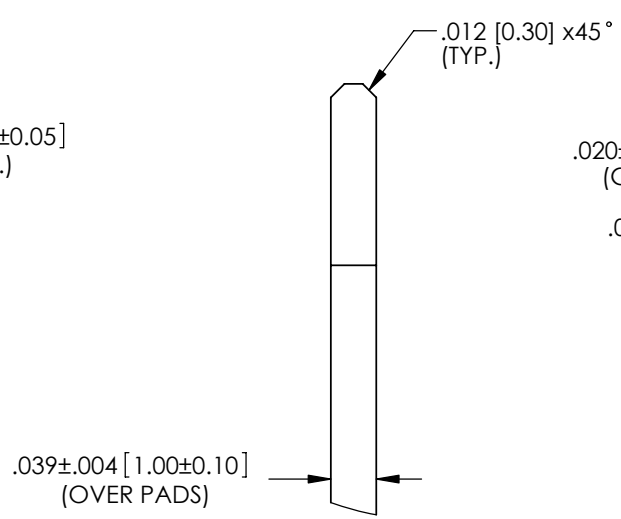
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DWG APPD			SCALE 4:1	PROJECT	SHEET 3 OF 7

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TOP VIEW OF BOAD



BOTTOM VIEW OF BOAD

RECOMMENDED LAYOUT DETAIL  
MATING TRANSCEIVER PCB

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NOTES;  
 1. DATUM AND BASIC DIMENTIONS ESTABLISHED BY CUSTOMER  
 2. PADS AND VIAS ARE CHASSIS GROUND, 11 PLACES.  
 3. THROUGH HOLES, PLATING OPTIONAL.



BSC  
(SEE NOTE 1)

$\phi .004 [0.10] \text{ (L) X F (S)}$   
 $\phi .004 [0.10] \text{ (L) X F (S)}$   
 (10 HOLES. SEE NOTE 2)

$\phi .033 \pm .002 [0.85 \pm 0.05]$   
 $\phi .004 [0.10] \text{ (S) X Y}$   
 -F-

COMPONENT AND TRACES KEEP-OUT (EXCEPT CHASSIS GROUND) (SEE NOTE 4)

THIS AREA DENOTES COMPONENT KEEP-OUT (TRACES ALLOWED)  
 CONNECTOR STANDOFFS AREA. COMPONENT AND TRACES KEEP-OUT (4 PLCS)

**RECOMMENDED SFP HOST BOARD LAYOUT  
 (ONE SIDE CAGE MOUNTING)**

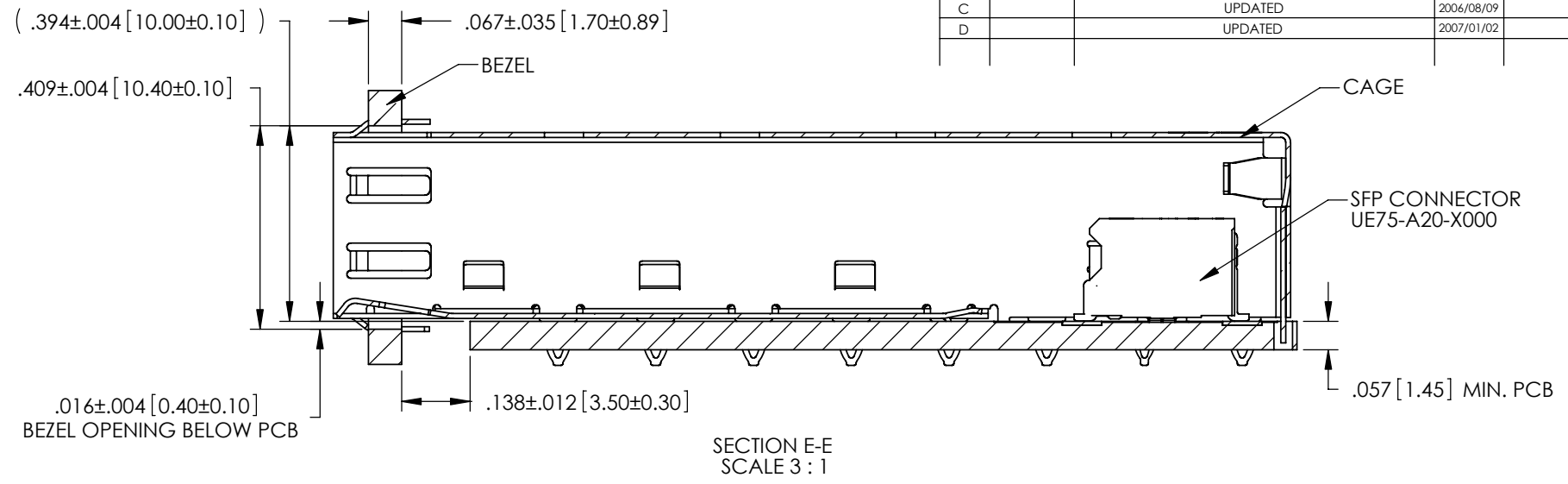
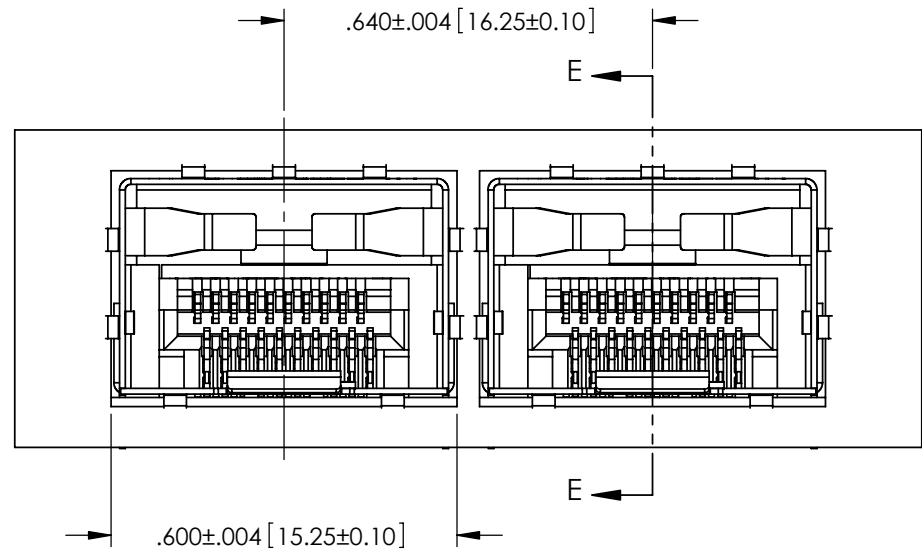
DETAIL H  
 SCALE 4 : 1

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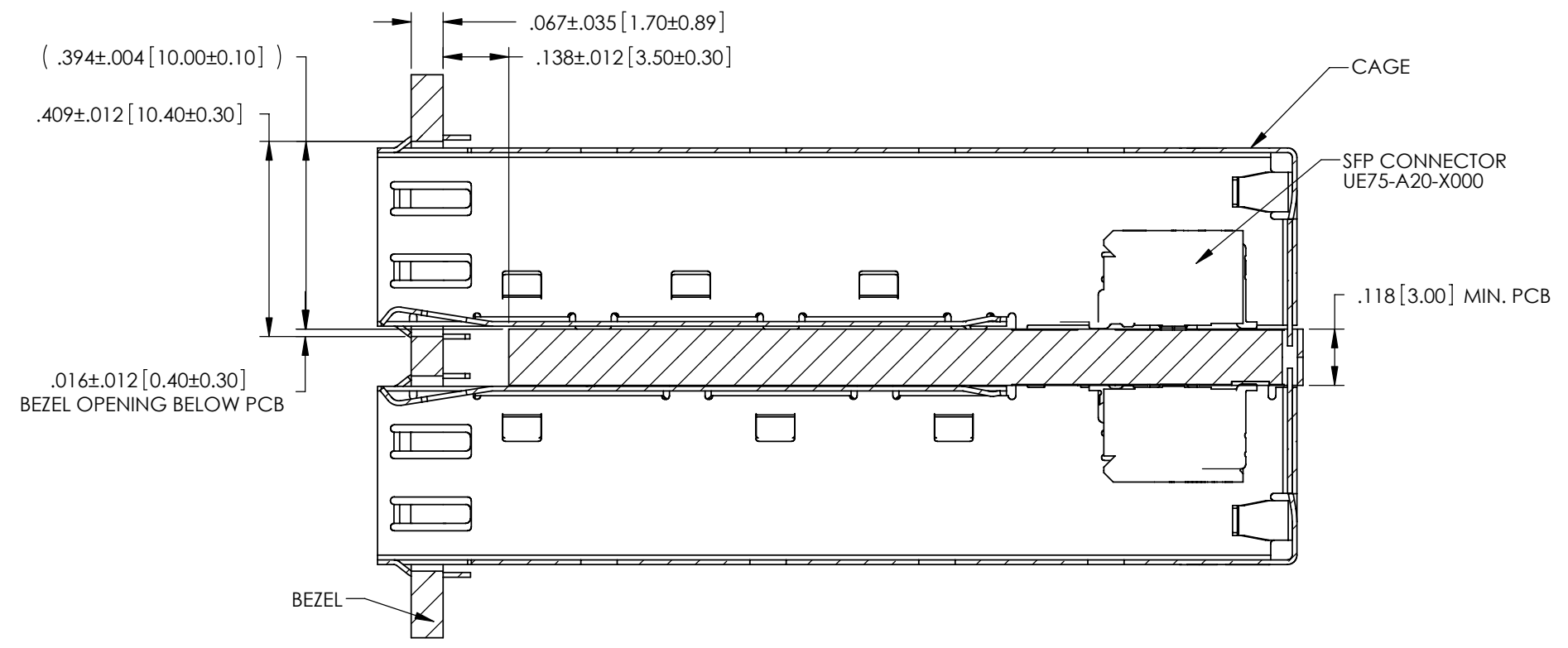
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RECOMMENDED BEZEL DESIGN  
(ONE SIDE CAGE MOUNTING)



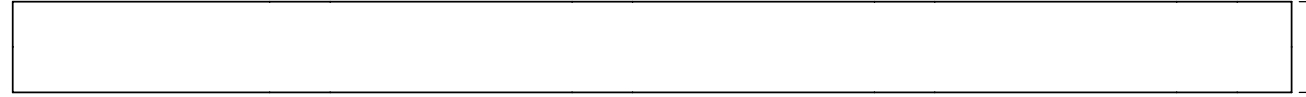
RECOMMENDED BEZEL DESIGN  
(BELLY TO BELLY CAGE MOUNTING)

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DWG APPD				

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RECOMMENDED SFP HOST BOARD LAYOUT  
(BELLY TO BELLY CAGE MOUNTING)

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DWG APPD					

## Данный компонент на территории Российской Федерации

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<http://moschip.ru/get-element>

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В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

### Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: [info@moschip.ru](mailto:info@moschip.ru)

Skype отдела продаж:

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